

REMARKS

Reconsideration of the above-referenced application in view of the following remarks is respectfully requested.

Claims 2, 4-10, 12, 15, 17, 18, 20, and 23 are pending in this application. Claims 2, 15, and 23 have been amended.

The drawings stand objected to as not showing an unpackaged semiconductor device as described in the specification. The claims have been amended to replace the word "unpackaged" with "un-encapsulated". Applicant respectfully points out that Figure 1F and Figure 1H show un-encapsulated semiconductor devices 133 (see also the text of the specification describing Figures 1F and 1H). Therefore, Applicant requests that the objection be withdrawn.

Claims 2-10, 12, 15, 17, 18, 20, and 23 stand rejected under 35 U.S.C. 112, first paragraph. Several of the claims have been amended to replace the word "unpackaged" with "un-encapsulated". In the substitute specification pages submitted by Applicant on 4/26/02 (unfortunately, no page numbers were provided), the portion of the text corresponding to Figure 1F includes the following statement: " . . . FIG. 1F depicts, in schematic cross section, multiple un-encapsulated IC chips 133, prepared for flip-chip assembly by having a plurality of fine-pitch electrical coupling members 134." In addition, the portion of the specification text corresponding to Figure 1H includes the following statement: "FIG. 1H shows as the result an assembly, generally designated 141, of flipped chips 133 and encapsulated devices 108, stacked vertically" Applicant therefore submits that the amended claims meet the relevant statutory requirements.

Claims 2, 4-10 and 15, 17, 18, and 23 stand rejected under 35 U.S.C. 102(e) as being anticipated by Inaba (JP 2001-217388). Claim 15, as amended, includes the feature wherein "said interconnector [has] on said first surface electrically conductive lines for connecting a plurality of separately encapsulated semiconductor devices formed on said first surface adjacent to each other." Inaba does not teach or suggest such a feature. Note that in Inaba's Figure 4, for example, chips 3 are unencapsulated. Claim 23, as amended, includes the step "forming on said first surface a plurality of separately encapsulated semiconductor devices adjacent to each other and connected to said conductive lines." As above, Inaba does not teach or suggest such a step. Therefore, Applicant respectfully submits that Claims 15 and 23 are patentable over Inaba. Claims 2, 4-10, 17, and 18 depend from Claims 15 and 23 and are therefore patentable over Inaba at least by virtue of their dependence from a patentable base claim.

Claims 4, 12, and 20 stand rejected under 35 U.S.C. 103(a) as being unpatentable over Inaba in view of Denes (U.S. Patent No. 5,220,488). Claims 4, 12, and 20 depend from Claims 15 and 23. As argued above, Inaba does not teach or suggest all of the features of Claims 15 and 23. Denes, cited for its teaching of passive electrical components, does not cure the deficiencies of Inaba with respect to Claims 15 and 23. Therefore, Applicant respectfully submits that Claims 4, 12, and 20 are patentable over the cited combination of references at least by virtue of their dependence upon a patentable base claim.

Claims 5 and 8 stand rejected under 35 U.S.C. 103(a) as being unpatentable over Inaba in view of Akram (U.S. Patent No. 6,214,716). Claims 5 and 8 depend from Claim 15. As argued above, Inaba does not teach or suggest all of the features of Claims 15. Akram, cited for its teachings relating to solder balls, does not cure the deficiencies of Inaba with respect to Claim 15. Therefore, Applicant respectfully submits that Claims 5 and 8 are patentable

over the cited combination of references at least by virtue of their dependence upon a patentable base claim.

Applicant respectfully requests reconsideration and withdrawal of the rejections and allowance of Claims 2, 4-10, 12, 15, 17, 18, 20, and 23. If the Examiner has any questions or other correspondence regarding this application, Applicant requests that the Examiner contact Applicant's attorney at the below listed telephone number and address.

Respectfully submitted,

A handwritten signature in black ink, appearing to read 'M. Skrehot', written in a cursive style.

Michael K. Skrehot
Reg. No. 36,682

Texas Instruments Incorporated
P.O. Box 655474, M/S 3999
Dallas, TX 75265
Phone: 972 917-5653
Fax: 972 917-4418